

RELIABILITY REPORT
FOR
MAX5920A/BESA+
PLASTIC ENCAPSULATED DEVICES

November 17, 2008

MAXIM INTEGRATED PRODUCTS

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Conclusion

The MAX5920AESA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I.Device Description	V.Quality Assurance Information
II.Manufacturing Information	VI.Reliability Evaluation
III.Packaging Information	IV.Die Information
.....Attachments	

I. Device Description

A. General

The MAX5920A/MAX5920B are hot-swap controllers that allow a circuit card to be safely hot plugged into a live backplane. The MAX5920A/MAX5920B operate from -20V to -80V and are well-suited for -48V power systems. These devices are pin and function compatible with the LT4250 and pin compatible with the LT1640. The MAX5920A/MAX5920B provide a controlled turn-on to circuit cards preventing glitches on the power-supply rail and damage to board connectors and components. The MAX5920A/MAX5920B provide undervoltage, overvoltage, and overcurrent protection. These devices ensure the input voltage is stable and within tolerance before applying power to the load. Both the MAX5920A and MAX5920B protect a system against overcurrent and short-circuit conditions by turning off the external MOSFET in the event of a fault condition. The MAX5920A/MAX5920B also provide protection against input voltage steps. During an input voltage step, the MAX5920A/MAX5920B limit the current drawn by the load to a safe level without turning off power to the load. Both devices feature an open-drain power-good status output (active-low PWRGD for the MAX5920A or PWRGD for the MAX5920B) that can be used to enable downstream converters. A built-in thermal-shutdown feature is also included to protect the external MOSFET in case of overheating. The MAX5920A/MAX5920B are available in an 8-pin SO package. Both devices are specified for the extended -40°C to +85°C temperature range.

II. Manufacturing Information

A. Description/Function:	-48V Hot-Swap Controller with External R _{SENSE}
B. Process:	BCD8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	ATP Philippines, UTL Thailand, Unisem Malaysia
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0356
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	128.4°C/W
M. Multi Layer Theta Jc:	36°C/W

IV. Die Information

A. Dimensions:	80 X 145 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 144 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 7.5 \times 10^{-9}$$

$\lambda = 7.5$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the BCD8 Process results in a FIT Rate of 2.3 @ 25C and 39.6 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The NP43 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114-D. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX5920AESA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	144	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data